

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT										
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Peter A. Gruber</td> <td>08/20/2007</td> </tr> <tr> <td>Donald W. Henderson</td> <td>08/17/2007</td> </tr> <tr> <td>Sung K. Kang</td> <td>08/20/2007</td> </tr> <tr> <td>Da-Yuan Shih</td> <td>08/20/2007</td> </tr> </tbody> </table>		Name	Execution Date	Peter A. Gruber	08/20/2007	Donald W. Henderson	08/17/2007	Sung K. Kang	08/20/2007	Da-Yuan Shih	08/20/2007
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Donald W. Henderson	08/17/2007										
Sung K. Kang	08/20/2007										
Da-Yuan Shih	08/20/2007										
<b>RECEIVING PARTY DATA</b>											
<b>Name:</b>	International Business Machines Corporation										
<b>Street Address:</b>	North Castle Drive										
<b>City:</b>	Armonk										
<b>State/Country:</b>	NEW YORK										
<b>Postal Code:</b>	10504										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11669076</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11669076						
Property Type	Number										
Application Number:	11669076										
<b>CORRESPONDENCE DATA</b>											
<b>Fax Number:</b>	(914)479-5304										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
<b>Phone:</b>	914 674 1094										
<b>Email:</b>	daveaker@optonline.net										
<b>Correspondent Name:</b>	David Aker										
<b>Address Line 1:</b>	23 Southern Road										
<b>Address Line 4:</b>	Hartsdale, NEW YORK 10530										
<b>ATTORNEY DOCKET NUMBER:</b>	YOR920060309US1										
<b>NAME OF SUBMITTER:</b>	David Aker										
Total Attachments: 2 source=YOR920060309US1Assign#page1.tif											

**CH \$40.00 11669076**



**ASSIGNMENT**

Docket No. YOR920060309US1

Whereas, we

INVENTOR  
AND CITY

(1) **Peter A. Gruber**  
County of **Westchester**  
and (2) **Donald W. Henderson**  
County of **Tompkins**  
and (3) **Sung K. Kang**  
County of **Westchester**  
and (4) **Da-Yuan Shih**  
County of **Dutchess**

of , Mohegan Lake  
and State of, New York  
of , Ithaca  
and State of, New York  
of , Chappaqua  
and State of, New York  
of , Poughkeepsie  
and State of, New York

have invented certain improvements in

TITLE

**MODIFICATION OF SOLDER ALLOY COMPOSITIONS TO SUPPRESS INTERF  
FORMATION IN SOLDER JOINTS**

DATES THAT

and filed on January 30, 2007, United States patent application serial number 11/669,076  
therefor and executed, respectively on

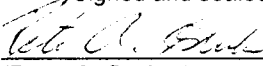
INVENTORS

SIGNED THE  
DECLARATION (1) August 20, 2007, (2) August , 2007,  
(3) August 20, 2007, (4) August 20, 2007.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of  
business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in  
the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby  
sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application  
and invention therein disclosed for the United States and foreign countries, and in all foreign countries, and all rights of  
priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue  
any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we  
hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary  
in connection with the United States and foreign applications when called upon to do so by IBM.

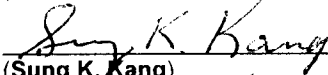
Signed and sealed

  
\_\_\_\_\_  
(Peter A. Gruber)

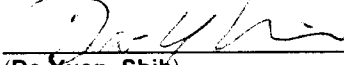
on August 20, 2007

\_\_\_\_\_  
(Donald W. Henderson)

on August , 2007

  
\_\_\_\_\_  
(Sung K. Kang)

on August 20, 2007

  
\_\_\_\_\_  
(Da-Yuan Shih)

on August 20, 2007

ASSIGNMENT

Docket No. YOR920060309US1

Whereas, we

INVENTOR AND CITY	(1) <b>Peter A. Gruber</b> County of <b>Westchester</b> and (2) <b>Donald W. Henderson</b> County of <b>Tompkins</b> and (3) <b>Sung K. Kang</b> County of <b>Westchester</b> and (4) <b>Da-Yuan Shih</b> County of <b>Dutchess</b>	of , Mohegan Lake and State of, New York of , Ithaca and State of, New York of , Chappaqua and State of, New York of , Poughkeepsie and State of, New York
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TITLE           **MODIFICATION OF SOLDER ALLOY COMPOSITIONS TO SUPPRESS INTERFACIAL VOID FORMATION IN SOLDER JOINTS**

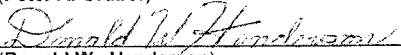
DATES THAT       and filed on January 30, 2007, United States patent application serial number 11/669,076 therefor and executed, respectively on

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Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and in all foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed

		on August		, 2007
(Peter A. Gruber)				
		on August	17	, 2007
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